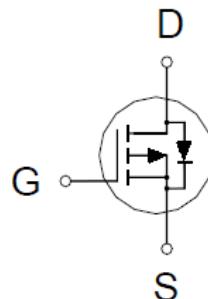
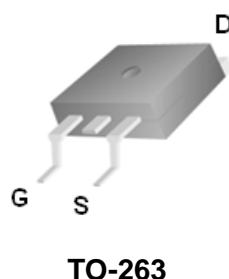


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P-Channel Enhancement Mode MOSFET

PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D
-60V	90mΩ @ $V_{GS} = 10V$	-18A



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ C$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS	SYMBOL	LIMITS	UNITS
Drain-Source Voltage	V_{DS}	-60	V
Gate-Source Voltage	V_{GS}	± 20	
Continuous Drain Current $T_C = 25^\circ C$	I_D	-18	A
		-12	
Pulsed Drain Current ¹	I_{DM}	-48	
Avalanche Current	I_{AS}	-22	
Avalanche Energy	E_{AS}	24	mJ
Power Dissipation $T_C = 25^\circ C$	P_D	54	W
		22	
Junction & Storage Temperature Range	T_J, T_{STG}	-55 to 150	°C

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Case	$R_{\theta JC}$		2.3	°C / W

¹limited by maximum junction temperature.

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ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$, Unless Otherwise Noted)

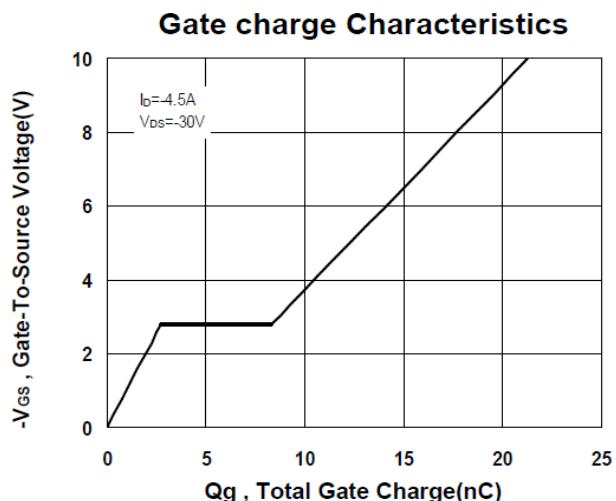
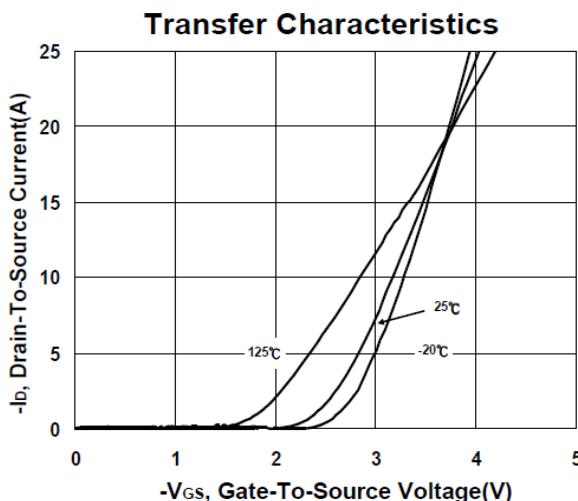
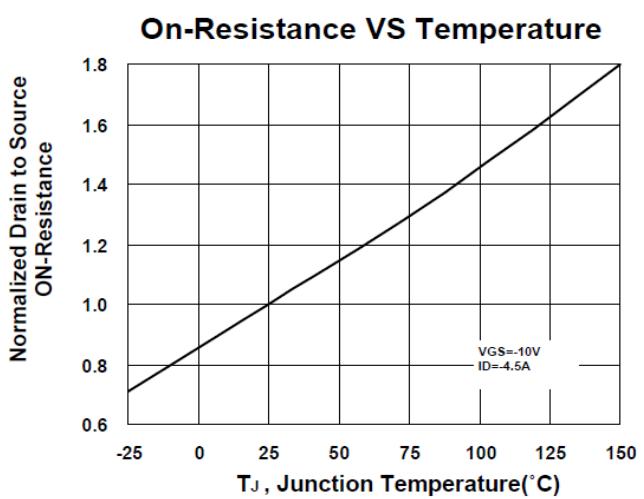
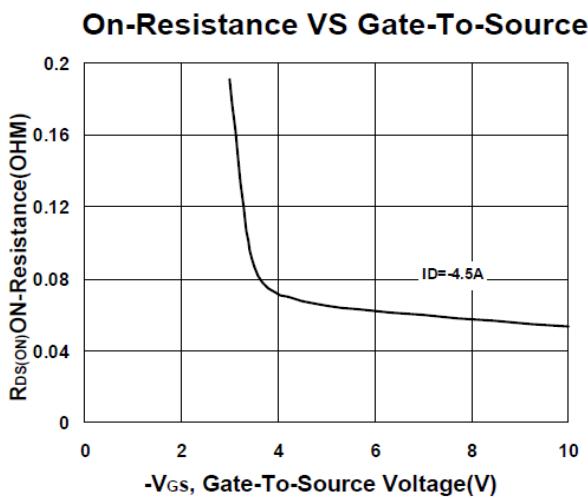
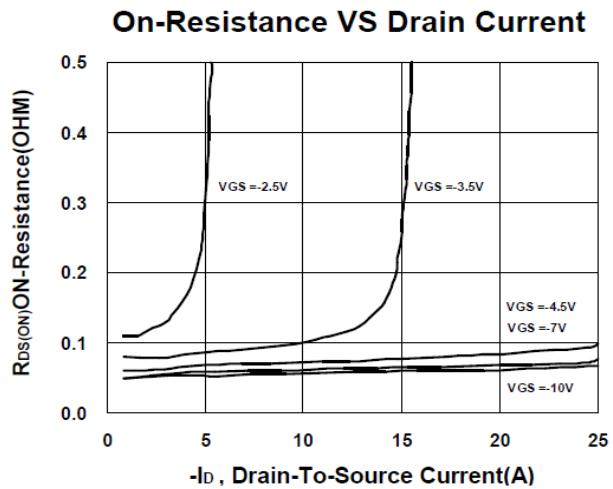
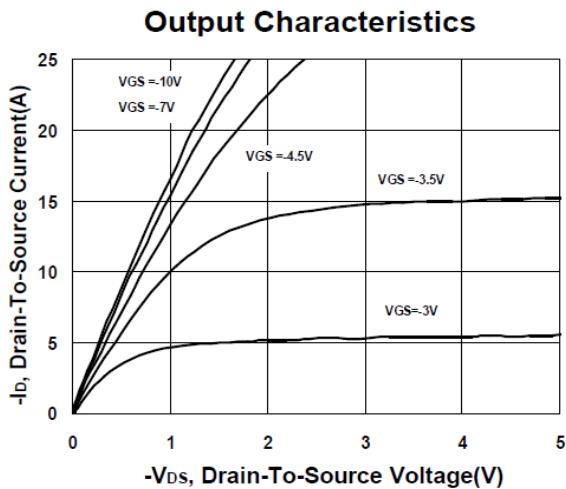
PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = -250\mu\text{A}$	-60			V
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = -250\mu\text{A}$	-1	-1.7	-3	
Gate-Body Leakage	I_{GSS}	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = \pm 20\text{V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = -48\text{V}, V_{\text{GS}} = 0\text{V}$			-1	μA
		$V_{\text{DS}} = -40\text{V}, V_{\text{GS}} = 0\text{V}, T_J = 125^\circ\text{C}$			-10	
On-State Drain Current ¹	$I_{\text{D}(\text{ON})}$	$V_{\text{DS}} = -5\text{V}, V_{\text{GS}} = -10\text{V}$	-48			A
Drain-Source On-State Resistance ¹	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}} = -4.5\text{V}, I_D = -3.5\text{A}$		70	135	$\text{m}\Omega$
		$V_{\text{GS}} = -10\text{V}, I_D = -4.5\text{A}$		54	90	
Forward Transconductance ¹	g_{fs}	$V_{\text{DS}} = -5\text{V}, I_D = -4.5\text{A}$		12		S
DYNAMIC						
Input Capacitance	C_{iss}	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = -25\text{V}, f = 1\text{MHz}$		1070		pF
Output Capacitance	C_{oss}			99		
Reverse Transfer Capacitance	C_{rss}			64		
Total Gate Charge ²	Q_g	$V_{\text{DS}} = 0.5V_{(\text{BR})\text{DSS}}, V_{\text{GS}} = -10\text{V}, I_D = -4.5\text{A}$		22		nC
Gate-Source Charge ²	Q_{gs}			3		
Gate-Drain Charge ²	Q_{gd}			6		
Turn-On Delay Time ²	$t_{\text{d}(\text{on})}$	$V_{\text{DS}} = -20\text{V}, I_D \approx -5\text{A}, V_{\text{GS}} = -10\text{V}, R_{\text{GEN}} = 6\Omega$		9		nS
Rise Time ²	t_r			15		
Turn-Off Delay Time ²	$t_{\text{d}(\text{off})}$			36		
Fall Time ²	t_f			11		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ($T_J = 25^\circ\text{C}$)						
Continuous Current	I_S				-18	A
Forward Voltage ¹	V_{SD}	$I_F = -4.5\text{A}, V_{\text{GS}} = 0\text{V}$			-1	V
Reverse Recovery Time	t_{rr}	$I_F = -4.5\text{A}, dI_F/dt = 100\text{A}/\mu\text{s}$		19		nS
Reverse Recovery Charge	Q_{rr}			14		nC

¹Pulse test : Pulse Width $\leq 300\ \mu\text{sec}$, Duty Cycle $\leq 2\%$.

²Independent of operating temperature.

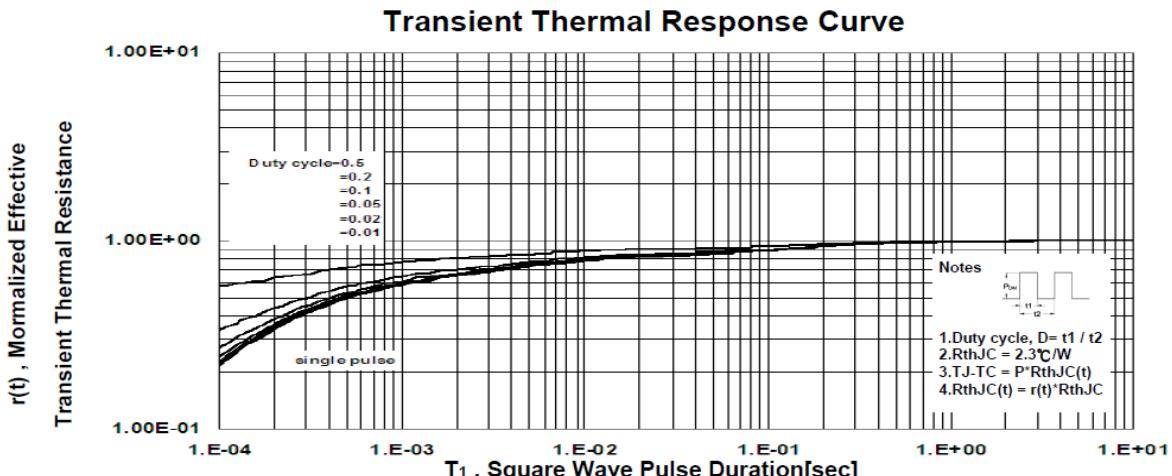
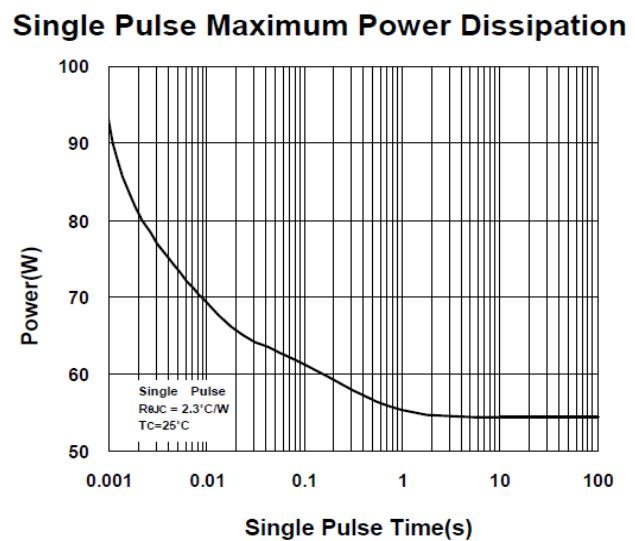
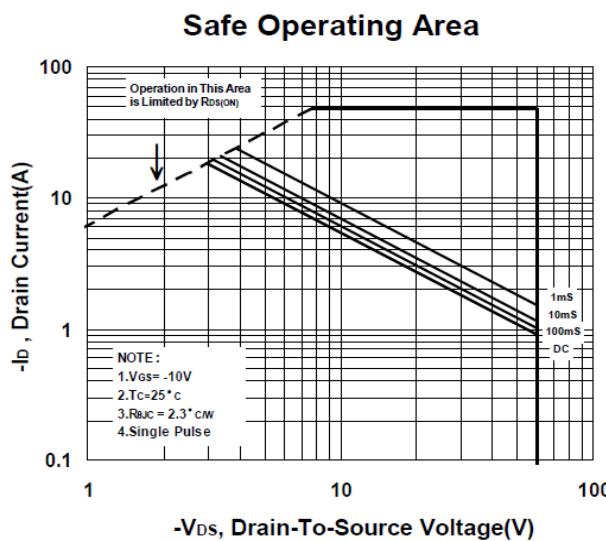
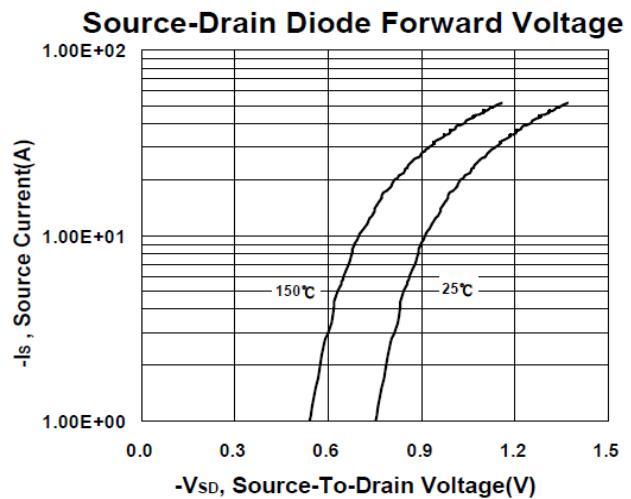
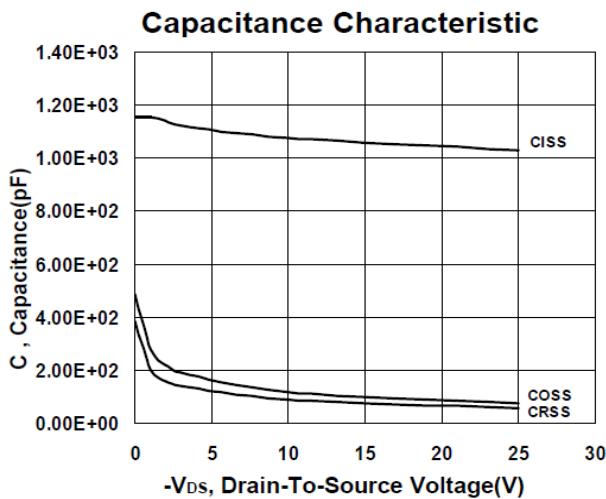
P9006ESG

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Package Dimension

TO-263 (D²PAK) MECHANICAL DATA

Dimension	mm			Dimension	mm		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	4.2		4.8	e	4.08	5.08	6.08
A1	0		0.3	E	9.8		10.55
b	0.71		1.06	E1	6.9		8.7
b2	1.07		1.47	H	14.2		15.8
C	0.3		0.69	L	1.2		2.79
C2	1.15		1.45	L1	1		1.65
D	8.3		9.4	L2	1.2		1.78
D1	6.37		8.23				

